



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2013-01-30
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Emilio Castelli	<b>Representative Title</b>	APG MD CHAMPION
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TDA7802D	A6ZS*UI09BC1	A	MU1A	2013-01-30
	Amount	UoM	Unit type	ST ECOPACK Grade
	1925.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	bright, annealed Tin/Silver/Bismuth	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	15.75x15.9x3.45	36	flat	
Comment				

Material Composition Declaration						Mfr Item Name	A625*UI09BC1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	27.003	mg	supplier	die	Silicon (Si)	7440-21-3		26.081	mg	965856	13549
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.2	mg	7407	104
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.159	mg	5888	83
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.042	mg	1555	22
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.342	mg	12665	178
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.015	mg	555	8
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.04	mg	1481	21
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.115	mg	4259	60
die (s)				supplier	back side metallization	Vanadium (V)	7440-62-2		0.009	mg	333	5
Leadframe	Copper & its alloys	1268.055	mg	supplier	alloy	Copper (Cu)	7440-50-8		1263.129	mg	996115	656171
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.582	mg	459	302
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		1.062	mg	838	552
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		3.282	mg	2588	1705
Die attach		15.295	mg	JIG Table A	glue or tape	Lead (Pb)	7439-92-1	7a-Lead in high me	14.913	mg	975025	7747
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		0.229	mg	14972	119
Die attach				supplier	glue or tape	Tin (Sn)	7440-31-5		0.153	mg	10003	79
Bonding wire		7.405		supplier	wire	Gold (Au)	7440-57-5		7.405	mg	1000000	3847
encapsulation		601.784	mg	supplier	mold compound	Phenol Resin	205830-20-2		24.072	mg	40001	12505
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		18.053	mg	29999	9378
encapsulation				supplier	mold compound	epoxy resin	na		18.053	mg	29999	9378
encapsulation				supplier	mold compound	carbon black	1333-86-4		1.204	mg	2001	625
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		540.402	mg	898000	280728
connections coating	Solder	5.458	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.458	mg	1000000	2835